Package Laser Marker

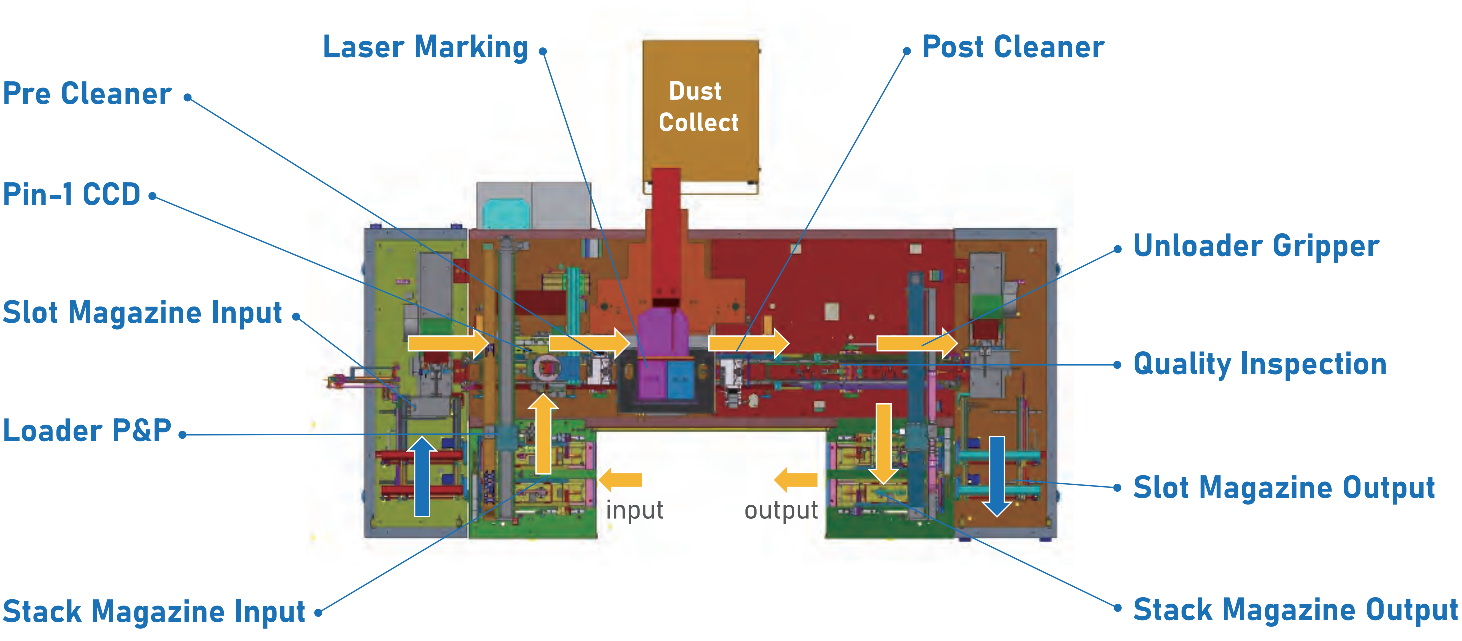
B2000TXL

Fully automatic laser marking system for lead frame and strip substrate laser package marking, available for both Stack and Slot Magazine. B2000 Series is also able to integrate the quality inspection function with X-Y table to fully inspect marking quality result.

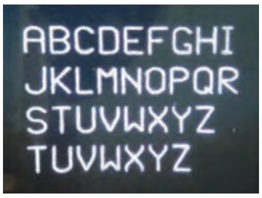
Feature

- Slot / Stack magazine type compatible
- Dual / Twin head applicable to double UPH
- Mark-out function(optional)
- SECs/GEM integration(optional)
- Simplified conversion kit design
  Change overtime < 10mins
- SECs/GEM integration(optional)

Process Flow

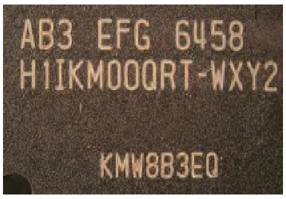


Sample Test



Bare Die

Heat Sink



Plastic Compound

Molding Compound

Specification

Machine Size	3200(H)x1700(D)x2000(W) mm(Stack + Slot)
Load-unload	Strip type 25-100mm(W) 180-300mm(L)
Load-unload Type & Qty	Stack / Slot Magazine 4~5 Depends on magazine size
Pin1 CCD Position	Top
Quality Inspection	5M Camera with X-Y table
Change Over Time	≦10 mins
Marking Accuracy	±100 um (with VPS ± 75um)

Laser Type	Fiber, IR, Green, UV Laser Dual / Twin Head
Laser Marking Area	300mm x 180mm(Max)
Carrier Type	Belt with Lifter
Dry Run Speed	SPH = 180 (Without Laser and QC time)
MTBA	> 4 hrs
MTBF	> 168 hrs

Optional High Flexibility for Customization

- Vision positioning system (VPS)
- Quality check system with 5M or 12M CCD
- Single, dual, twin laser system available
- Additional 2D reader system
- 2D mark out function
- SECs/GEM communication protocal
- Additional pre / post cleaning